



Product Change Notification / BLAS-28XZGK309

Date:

13-May-2024

Product Category:

8-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6736 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

Affected CPNs:

[BLAS-28XZGK309_Affected_CPN_05132024.pdf](#)
[BLAS-28XZGK309_Affected_CPN_05132024.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

Pre and Post Change Summary:

		Pre Change	Post Change	
Assembly Site		Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material		Au	Au	CuPdAu
Die Attach Material		3280	3280	3280
Molding Compound Material		G700LTD	G700LTD	G700LTD
Lead-Frame Material		C194	C194	C194

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MP3A assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:June 7, 2024 (date code: 2423)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2024					>	May 2024					June 2024				
	05	06	07	08	09		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date	x															
Qual Report Availability								x								
Final PCN Issue Date									x							
Estimated Implementation Date											x					

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 01, 2024: Issued initial notification.

May 13, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 7, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_BLAS-28XZGK309_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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